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TITLE : LEADLESS SOLDER

ABSTRACT : PURPOSE: To lower the melting temp. of leadless solder and to improve wettability and mechanical strength by composing the leadless solder of specific weight% of Ag, Cu and the balance Sn.

CONSTITUTION: The leadless solder is formed of an Sn-Ag-Cu system. The compsn. thereof is formed of the balance Sn, 0.5 to 3.5wt.% Ag, 0.5 to 2.0wt.% Cu. There is an effect of lowering the melting temp. and improving the mechanical strength by adding the Ag to the essential component Sn. Further, the microstructures are formed and the mechanical strength is further improved by adding the Cu to the compsn. This leadless solder is used by molding the compsn. to various forms, such as rods, wires, ribbons, preforms and powders. As a result, the long-term stable supply is possible and the leadless solder is provided at a relatively low cost.

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